

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY						
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
30	0.0030 at V _{GS} = 10 V	38	27.5 nC			
50	0.0038 at V _{GS} = 4.5 V	33	27.5110			

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- SkyFET[®] Monolithic TrenchFET[®] Gen III Power MOSFET and Schottky Diode
 100 % R_g and UIS Tested

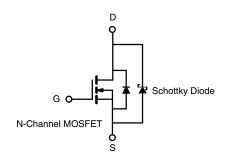
COMPLIANT HALOGEN

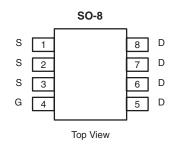
RoHS

Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Notebook CPU Core
- Buck Converter





Ordering Information: Si4628DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage	V _{GS}	± 20			
	T _C = 25 °C		38	- A	
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 70 °C	1-	30		
Continuous Diain Ourient (1j = 150°C)	T _A = 25 °C	I _D	25.4 ^{b, c}		
	T _A = 70 °C		20 ^{b, c}		
Pulsed Drain Current		I _{DM}	70		
Continuous Source-Drain Diode Current	T _C = 25 °C	L.	7		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.1 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	45		
Single Pulse Avalanche Energy		E _{AS}	101	mJ	
	T _C = 25 °C		7.8		
Maximum Bower Dissinction	T _C = 70 °C	PD	5	w	
Maximum Power Dissipation	T _A = 25 °C	۲D -	3.5 ^{b, c}		
	T _A = 70 °C		2.2 ^{b, c}	7	
Operating Junction and Storage Temperature Range	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Тур.	Max.	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	29	35	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	13	16	0/10		

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 80 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					<u> </u>		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 1 mA$	30			V	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 1 \text{ mA}$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	0.10 0.25		0.25		
		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 100 ^{\circ}\text{C}$		7.5	70	– mA	
On -State Drain Current ^a	I _{D(on)}	$V_{DS} \geq 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	40			Α	
	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		0.0024	0.0030	Ω	
Drain-Source On-State Resistance ^a		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 15 \text{ A}$		0.0030	0.0038		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		73		S	
Dynamic ^b							
Input Capacitance	C _{iss}			3450		pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		810			
Reverse Transfer Capacitance	C _{rss}	1		260			
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		58	87		
				27.5	42	nC	
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 20 A		8.3		nc	
Gate-Drain Charge	Q _{gd}			7.5			
Gate Resistance	R _g	f = 1 MHz	0.4	1.7	3.4	Ω	
Turn-On Delay Time	t _{d(on)}			28	55		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		20	40		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		39	75		
Fall Time	t _f	1		13	26		
Turn-On Delay Time	t _{d(on)}			12	24	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		36	70		
Fall Time	t _f	1 1		9	18		
Drain-Source Body Diode and Schottky	Characterist	tics			· .		
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C			7		
Pulse Diode Forward Current ^a	I _{SM}				70	A	
Body Diode Voltage	V _{SD}	I _S = 2 A		0.44	0.53	V	
Body Diode Reverse Recovery Time	t _{rr}			28	55	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			21	42	nC	
Reverse Recovery Fall Time	t _a	I _F = 13 A, dl/dt = 100 A/μs, T _J = 25 °C –		15			
Reverse Recovery Rise Time	t _b	1		13		ns	

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

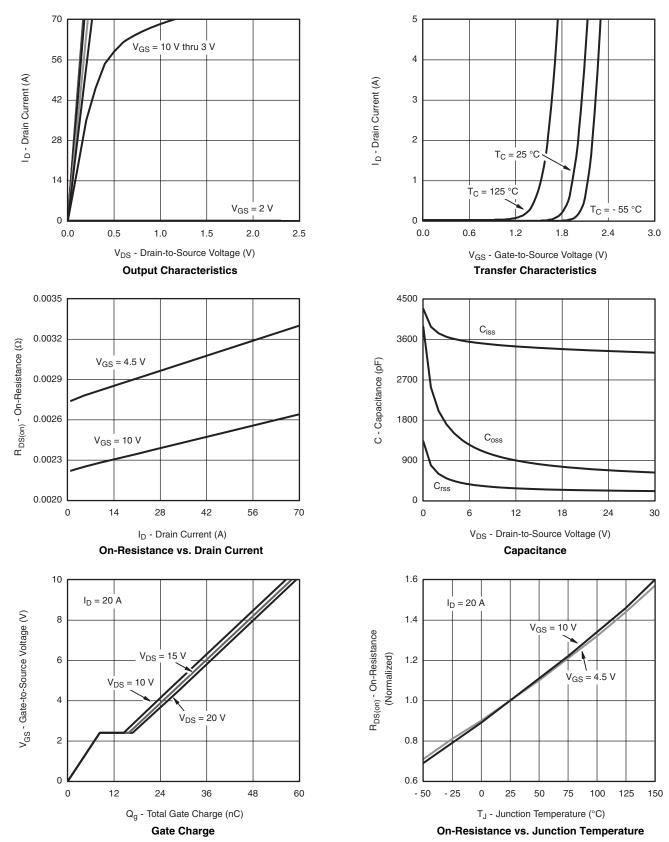
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Si4628DY

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



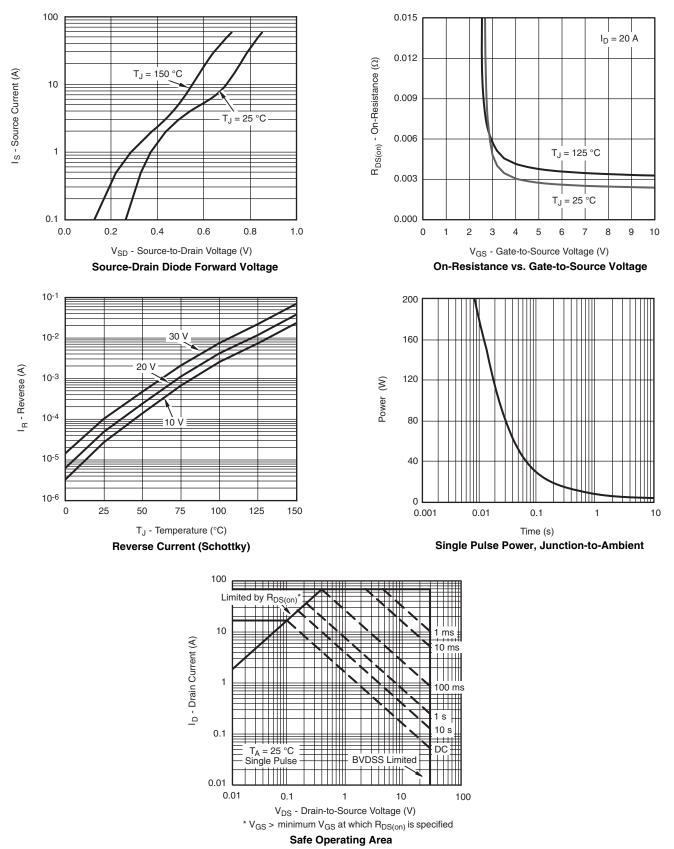
Document Number: 64811 S09-0871-Rev. A, 18-May-09

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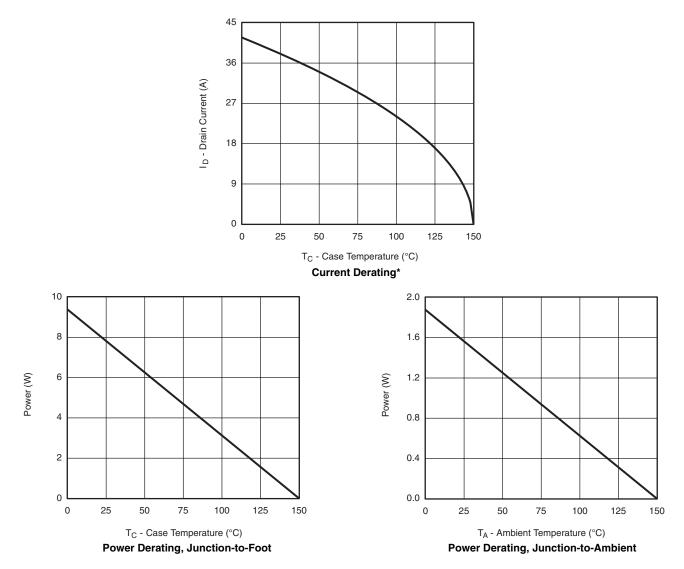
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Si4628DY Vishay Siliconix

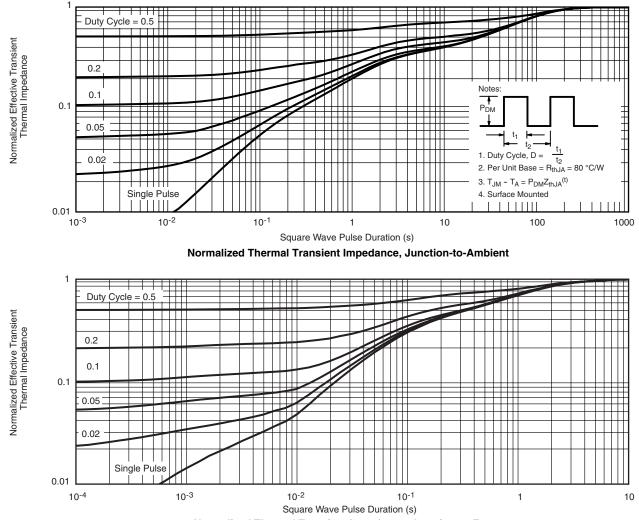
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?64811.



Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						

Application Note 826

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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